

High Performance FR4

Laminate: R - 1755V

Prepreg: R - 1650V

Standard size warp weft mm	Copper foil thickness	Laminate thickness	Thickness tolerance
920 x 1220		Thin laminates (excluding Copper foil thickness)	according to IPC - 4101 B B - (C)
1160 x 1060	0,018 mm		
1060 x 1220	0,035 mm	—————	
1110 x 1220	0,070 mm		
1060 x 1280		Rigid laminates (including Copper foil thickness)	according to IPC - 4101 B L - (M)

Other thicknesses on request



[Features]

- ▶ High performance FR4 material for PCB production
- ▶ Tg 170° C by DSC method
- ▶ Phenolic cured, excellent through-hole reliability, low CTE-Z
- ▶ Excellent heat resistance, low water absorption
- ▶ Excellent CAF resistance
- ▶ For lead free assembly
- ▶ Conforms to the most important international Standards
IPC-4101B/126, UL 94, IPC-4562, UL 746
- ▶ Clear prepreg available
- ▶ UV-blocking
- ▶ Workability: with standard FR4 process

[Applications]

Automotive, Network equipment (server, routers), Measuring instruments, etc